

10 9 8 7 6 5 4 3 2 1

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53261-****	WAFER ASSY	MODEL NO./MATERIAL NO.
50079-****	TERMINAL	
51021-****	HOUSING	

RELEASED EC NO: J2006-2426 DRWN: A0YAGI 2006/02/02 CHKD: YMAEDA 2006/02/03 APPR: NUKITA 2006/02/07	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
	10 UNDER	± ---	DRAWN BY Y. A0YAGI	DATE 2006/01/30	TITLE 1.25 W-TO-B CONN. 51021,53261 MATING CROSS SECTION				
	10 OVER 30 UNDER	± ---	CHECKED BY Y. MAEDA	DATE 2006/01/30	MOLEX INCORPORATED				
	30 OVER	± ---	APPROVED BY N. UKITA	DATE 2006/01/30	MATERIAL NO. SEE CHART		DOCUMENT NO. SD-51021-002	SHEET NO. 1 OF 1	
	ANGULAR ± --- °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				

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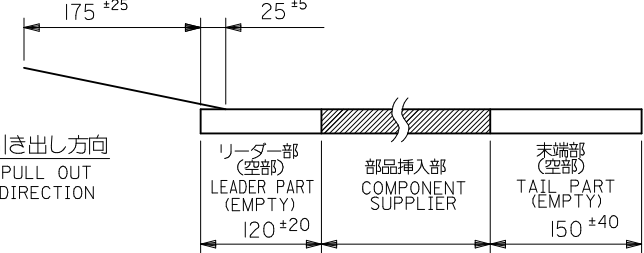
4

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注記
NOTES

- 53261-**-19 の詳細寸法については図面 SD-53261-024 を参照下さい。
RE DETAILED DIMENSIONS, SEE SD-53261-024
- 梱包数量: 1000個/リール
NUMBER OF CONNECTOR: 1000PCS/REEL
- リードテープ長さ LEAD TAPE LENGTH
トップテープリーダー部 TOP TAPE LEADER PART
トップテープ未接着部 TOP TAPE NON-BONDED PART



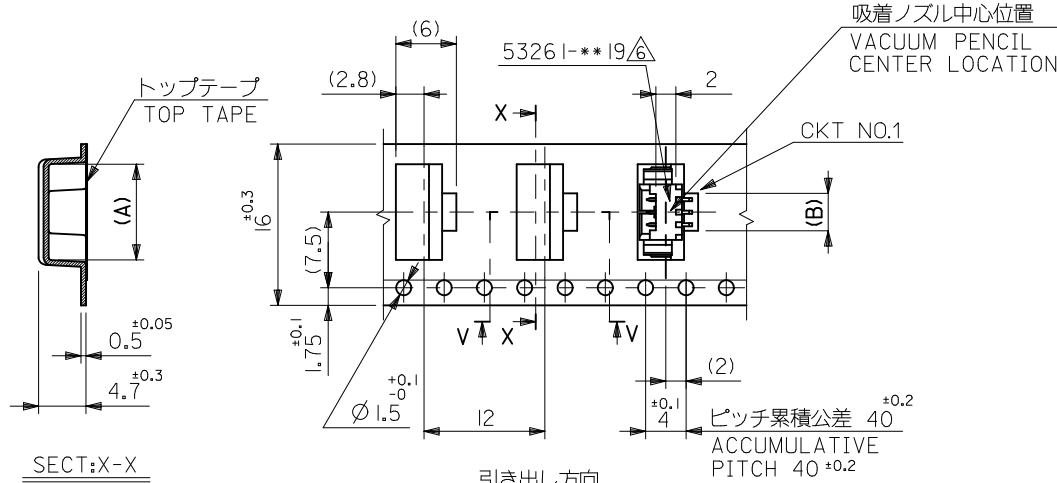
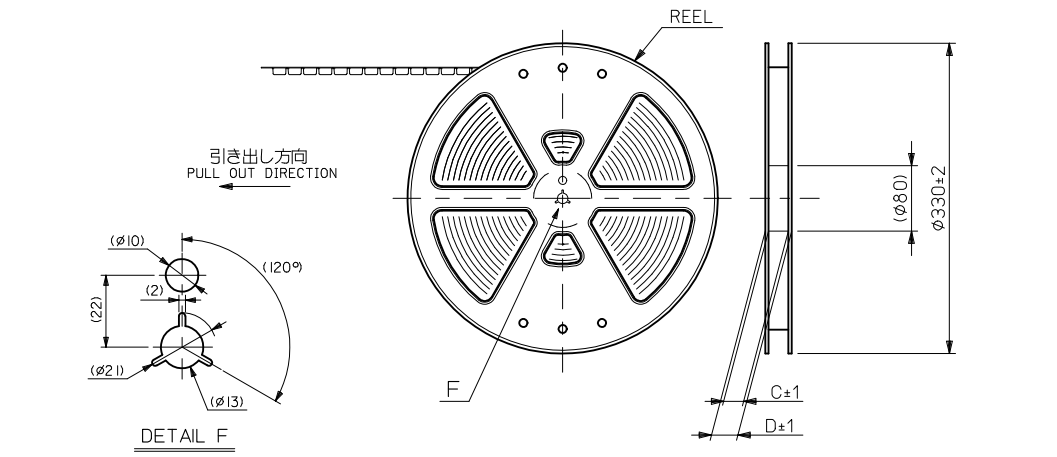
- 材料 (MATERIAL)
キャリアテープ (CARRIER TAPE): ポリプロピレン (POLYPROPYLENE)
トップテープ (TOP TAPE): PET, PE, PEF
リール (REEL): ポリスチレン (PS) <リサイクル材含む>
POLYSTYRENE (PS) <RECYCLE MATERIAL CONTAINED>

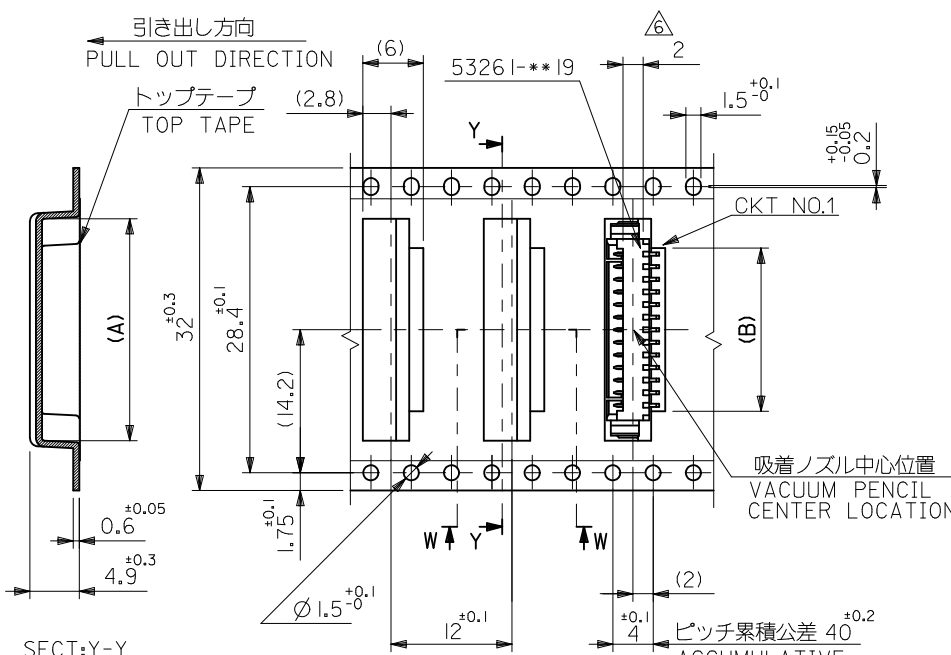
△ コネクタ、ハウジング平面部
CONNECTOR, HOUSING FLAT AREA

- 本製品は 53261-**-90 の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 53261-**-90
- ELV及びRoHS適合品
ELV AND RoHS COMPLIANT
- 本製品は乾燥剤入り、ハイバリア梱包仕様である。
THIS PRODUCT IS HIGH BARRIER PACKAGE WITH DESICCANT.

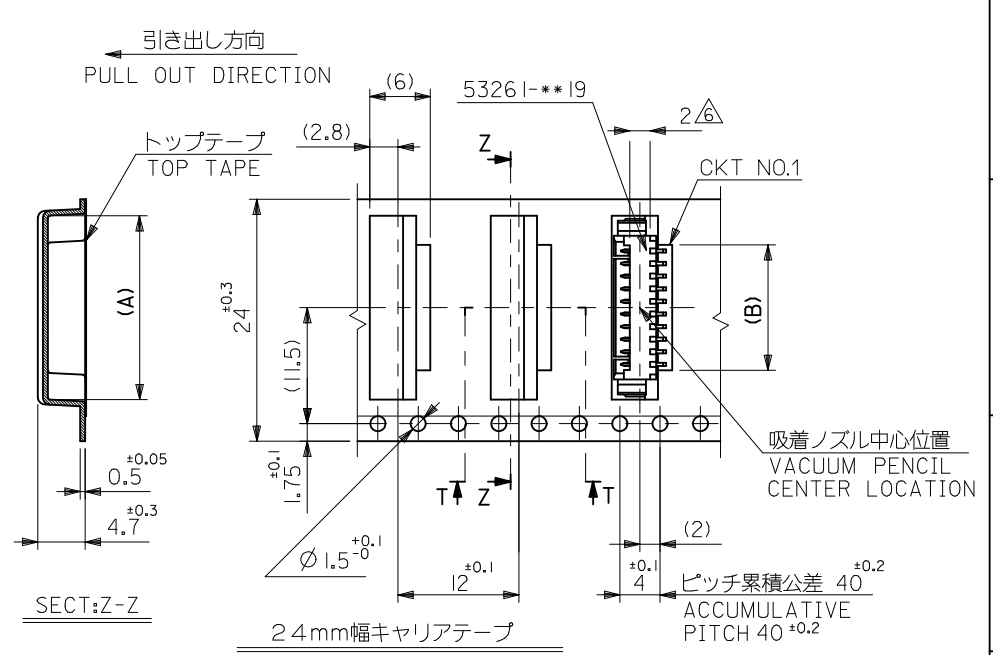
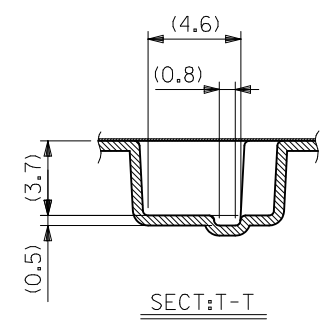
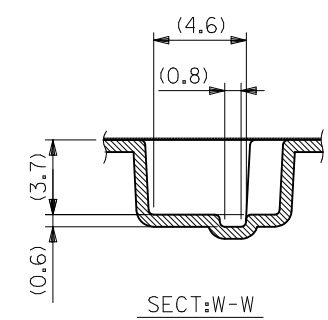
16	21.4	17.4	3.7	9.5	53261-0371	3				
			2.45	8.25	53261-0271	2				
キャリアテープ幅 CARRIER TAPE WIDTH					D	C	B	A	EMBOSSD TAPE PACKAGE オーダー番号 ORDER NO.	極数 CKT.

REVISED	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE MM ONLY	SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
EC NO: D	2010/02/17 DRWN: YGOTO CHKD: KASAKAWA APPR:	10 UNDER ±0.2 10 OVER 30 UNDER ±0.25 30 OVER ±0.3 ANGULAR ±3 ° DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	DRAWN BY: H. SHIMABUKUR DATE: '04/02/06 CHECKED BY: K. TOJO DATE: '04/02/06 APPROVED BY: NUKITA DATE: 2010/02/18	TITLE 1.25 W/B CONN WAFER ASSY FOR SMT EMBSTP PKG	MATERIAL NO. SEE TABLE & SHEET 2,3	DOCUMENT NO. SD-53261-023
REV			SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		





32mm幅キャリアテープ
32mm WIDTH CARRIER TAPE

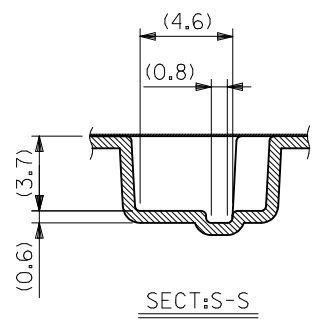
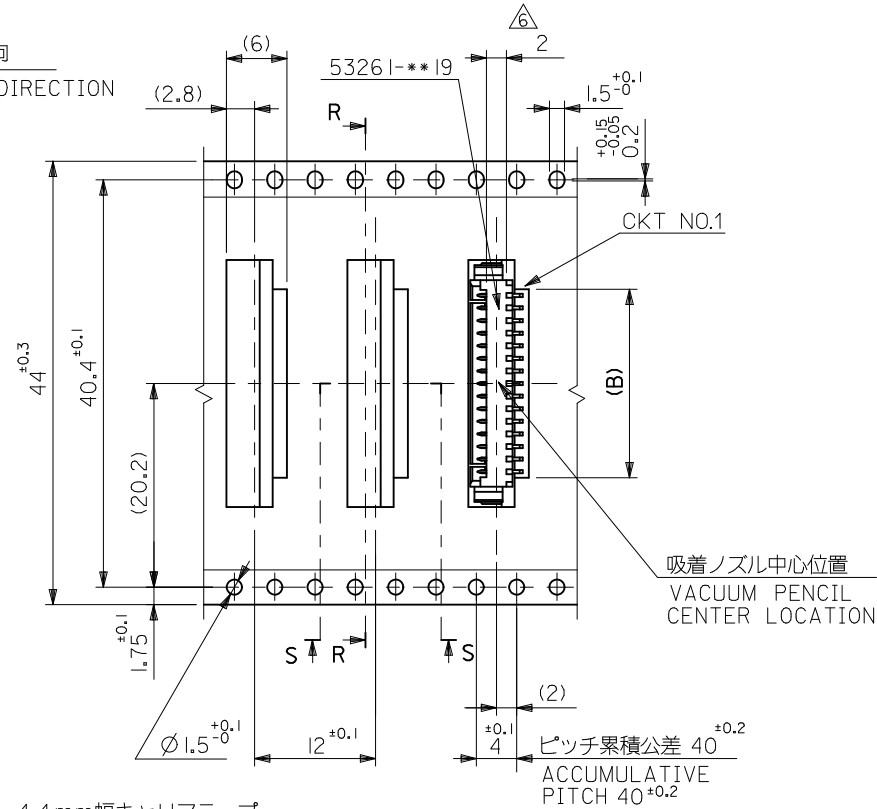
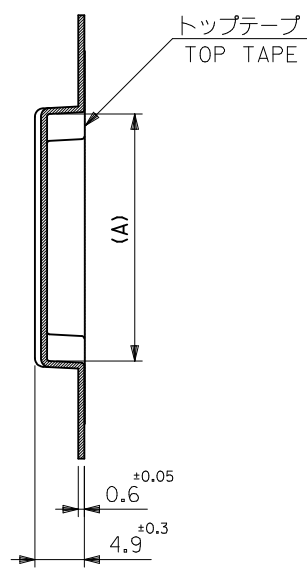


24mm幅キャリアテープ
24mm WIDTH CARRIER TAPE

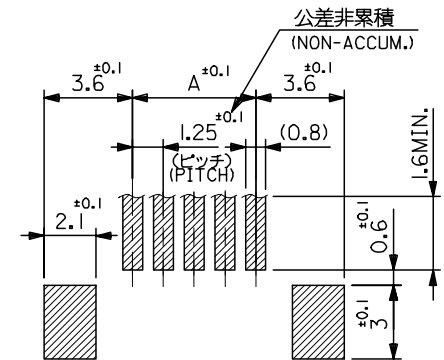
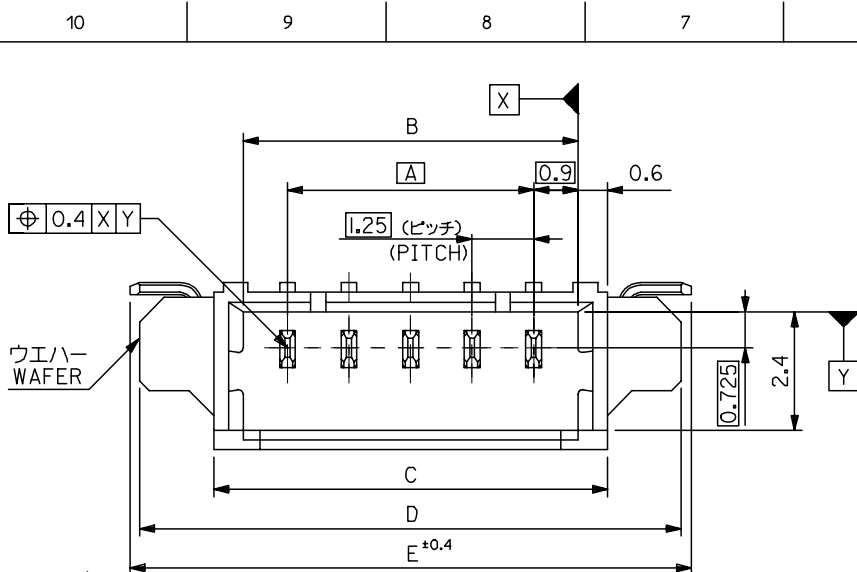
32	37.4	33.4	16.2	22	53261-1371	13
			14.95	20.75	-1271	12
24	29.4	25.4	13.7	19.5	-1171	11
			12.45	18.25	-1071	10
			11.2	17	-0971	9
			9.95	15.75	-0871	8
			8.7	14.5	-0771	7
			7.45	13.25	-0671	6
			6.2	12	-0571	5
4.95	10.75	53261-0471	4			

MODEL NO.	53261-***71	キャリアテープ幅 CARRIER TAPE WIDTH	D	C	B	A	EMBOSSD TAPE PACKAGE オーダー番号 ORDER NO.	極数 CKT.
REVISED	2010/02/17	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC		
EC NO.	DRWN:YGOITO CHKD:KASAKAWA APPR:	10 UNDER ±0.2	DRAWN BY DATE H. SHIMABUKUR '04/02/06		TITLE 1.25 W/B CONN WAFER ASSY FOR SMT EMBSTP PKG			
REV		10 OVER 30 UNDER ±0.25	CHECKED BY DATE K. TOJO '04/02/06		MOLEX INCORPORATED			
		30 OVER ±0.3	APPROVED BY DATE NUKITA 2010/02/18		DOCUMENT NO. SD-53261-023			
		ANGULAR ±3 °	MATERIAL NO. SEE TABLE & SHEET 1.3		SHEET NO. 2 OF 3			
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

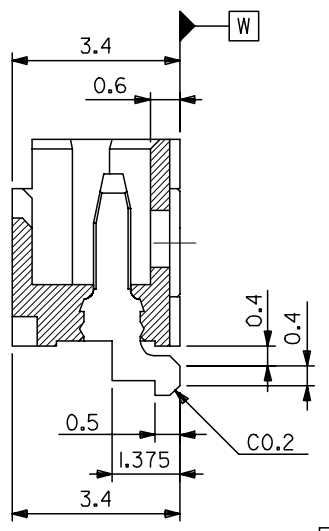
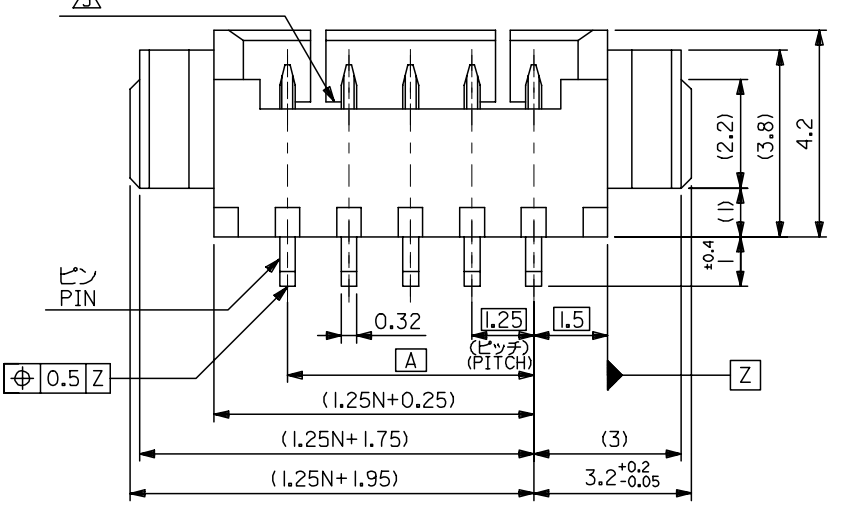
引き出し方向
PULL OUT DIRECTION



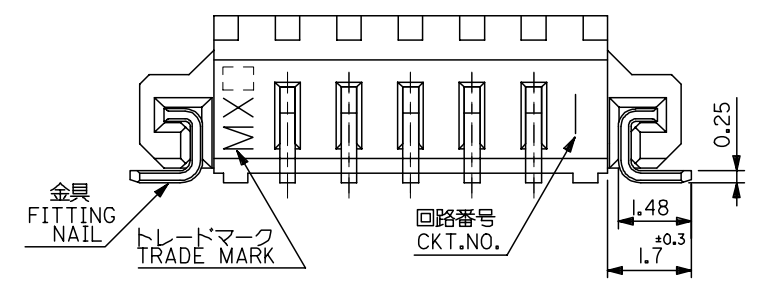
MODEL NO.	53261-***71	44	49.4	45.4	18.7	24.5	53261-1571	15	
					17.45	23.25	53261-1471	14	
		キャリアテープ幅 CARRIER TAPE WIDTH	D	C	B	A	EMBOSSD TAPE PACKAGE オーダー番号 ORDER NO.	極数 CKT.	
REVISED	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)			DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
EC NO:	2010/02/17	10 UNDER	±0.2	DRAWN BY H. SHIMABUKUR		DATE '04/02/06	TITLE 1.25 W/B CONN WAFER ASSY FOR SMT EMBSTP PKG		
DRWN:	Y.GOTO	10 OVER 30 UNDER	±0.25	CHECKED BY K. TOJO		DATE '04/02/06	MOLEX INCORPORATED		
CHKD:	KASAKAWA	30 OVER	±0.3	APPROVED BY NUKITA		DATE 2010/02/18			
APPR:		ANGULAR ±3 °		MATERIAL NO. SEE TABLE & SHEET 12		DOCUMENT NO. SD-53261-023	SHEET NO. 3 OF 3		
REV		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					



参考基板レイアウト
RECOMMENDED P.C.BOARD PATTERN DIM.(REF.)
(SCALE 5:1)



[断面図]
[CROSS SECTION]



注記 NOTES

1. 嵌合相手: 51021 シリウス
MATES WITH: 51021 SERIES
2. 材質 MATERIAL
ウエハー: NYLON46, UL94V-0
ピン: リン青銅
PIN: PHOS-BRO
: 銅メッキ 1. 0マイクrometer以上
: TIN 1.0 MICROMETER MINIMUM
: ニッケル下地 1. 0マイクrometer以上
: NICKEL(UNDER PLATING)1.0 MICROMETER MINIMUM
金具
FITTING NAIL: リン青銅
: PHOS-BRO
: 銅メッキ 1. 0マイクrometer以上
: TIN 1.0 MICROMETER MINIMUM
: ニッケル下地 1. 0マイクrometer以上
: NICKEL(UNDER PLATING)1.0 MICROMETER MINIMUM
- △ ロック窓は2, 3極は1箇所, 4極以上は2箇所とする。
LOCKING WINDOW:
ONE PLACE FOR 2 AND 3 CKT. AND
TWO PLACES FOR MORE THAN 3 CKT.
4. ソルダーテール部のスレ量及び金具(補強板)のスレ量は基準面[W]に対し、上方向0.05 MAX.、下方向に0.1 MAX.とする。[W] OFFSET BETWEEN BASIS PLANE TO SOLDER TAIL BOTTOM AND FITTING NAIL BOTTOM:
UPPER SIDE: 0.05MAX.
LOWER SIDE: 0.1MAX.
5. 本製品は 53261-**-10 の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 53261-**-10

26.4	26	23	21.8	20	53261-1719	17	
23.9	23.5	20.5	19.3	17.5	-1519	15	
22.65	22.25	19.25	18.05	16.25	-1419	14	
21.4	21	18	16.8	15	-1319	13	
20.15	19.75	16.75	15.55	13.75	-1219	12	
18.9	18.5	15.5	14.3	12.5	-1119	11	
17.65	17.25	14.25	13.05	11.25	-1019	10	
16.4	16	13	11.8	10	-0919	9	
15.15	14.75	11.75	10.55	8.75	-0819	8	
13.9	13.5	10.5	9.3	7.5	-0719	7	
12.65	12.25	9.25	8.05	6.25	-0619	6	
11.4	11	8	6.8	5	-0519	5	
10.15	9.75	6.75	5.55	3.75	-0419	4	
8.9	8.5	5.5	4.3	2.5	-0319	3	
53261-**-19	7.65	7.25	4.25	3.05	1.25	53261-0219	2

MODEL NO.	E	D	C	B	A	MATERIAL. NO.	極数 CKT.
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REVISED EC NO: J2005-3130 DRW:NAIDA 2005/04/19 CHK:KTOYODA 2005/04/21 APPR:NUKITA 2005/04/25	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY HSHIMABU	DATE 04/02/06	TITLE 1.25 WIRE TO BOARD WAFER ASS FOR SMT -LEAD FREE-		
	10 OVER 30 UNDER	±0.25	CHECKED BY KTOJO	DATE 04/02/06	MOLEX INCORPORATED		
	30 OVER	±0.3	APPROVED BY MSASAO	DATE 04/02/06	DOCUMENT NO. SD-53261-024		
	ANGULAR	±3 °	MATERIAL NO.		SHEET NO. 1 OF 1		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE DRAWING		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			